

EDUCATION

- University of California, Berkeley** GPA: 4.0/4.0
Exchange Student in Electrical Engineering & Computer Science Jan. 2024 – June 2024
- Coursework: Computer Architecture and Engineering, Introduction to Digital Design and Integrated Circuits, Application Specific Integrated Circuits Laboratory
- National Tsing Hua University**, Hsinchu, Taiwan GPA: 4.26/4.3 (Last 2y), 3.97/4.3 (Overall)
B.S. in Electrical Engineering: Sep. 2020 – Jan. 2024
- Coursework: Introduction to Integrated Circuit Design, Integrated Circuit Design Laboratory, Computer Architecture, Algorithms, Embedded System Laboratory, Machine Learning
-

PROFESSIONAL EXPERIENCE

- SiFive, Inc. – RTL Design Engineer** Nov. 2024 – Present
- Integrated new ISA features such as SiFive Scalar Coprocessor Interface into in-order RISC-V CPU cores for Essential, Intelligence, and Automotive series
 - Built detailed instruction tracking system that monitors the complete lifecycle across all pipeline stages, enabling performance bottleneck analysis and RVWMO compliance check
 - Discovered 5+ critical hang scenarios by implementing automated assertion checker using Chisel HDL
 - Validated Control and Status Register functionality with automated read/write mask generation
- Micron Technology – ASIC Design Engineer Intern** Jul. 2024 – Aug. 2024
- Improved Clock-Domain-Crossing multi-flop identification by refining Spyglass report extraction, reducing analysis time by 25%
 - Automated Register Models and RTL implementations comparison, cutting comparison time to 1/10
 - Resolving mismatches between RTL design and specs documentation
-

RESEARCH & PROJECTS

- A 22nm Non-Volatile ReRAM Compute-in-Memory (CIM) Edge-AI Processor**
National Tsing Hua University (Memory Lab) Dec. 2025 – June 2026 (Expected)
- Integrate the heterogeneous memory systems, including SRAM CIM macros, RRAM CIM macros, and standard SRAM, into Rocket Chip and leveraged RoCC Interface to communicate
 - Extended the Rocket Core with custom instructions for CIM macros
 - Deploy neuro-symbolic models on the CPU-CIM systems, enabling performance benchmarking against previous approaches
- Laboratory for Computer Architecture and Engineering**
University of California, Berkeley Jan. 2024 – June 2024
- Optimized RISC-V processors such as Rocket Core and Berkeley Out-of-Order Machine in Chisel
 - Decreased 13.2% of average memory access time by implementing victim cache with LRU replacement policy
 - Reduced miss rates under 15% for all benchmarks by designing branch predictors on out-of-order processors
-

- RISC-V ISA implementation on a 3-stage CPU integrated with SRAM**
University of California, Berkeley Jan. 2024 – June 2024
- Designed a 3-stage RISC-V CPU, including ALU design, Core implementation, and memory system implementation, and upgraded up to 5-stage for better performance
 - Incorporated bypass units and stall units to reduce Cycle Per Instruction (CPI) by 12%
 - Built custom 4-way I/D caches using SRAM macros, reduced 30% conflict miss and shortened critical path by 4ns through SRAM-aware placement
 - Refined SRAM placement to shorten the critical path by 4ns

Five-Stage CPU for RISC-V ISA (RV32I)

National Tsing Hua University (IC Design Lab)

Sep. 2023 – Jan. 2024

- Developed a 5-stage RISC-V CPU in Verilog and completed full ASIC flow including RTL simulation, synthesis, auto place-and-route, and post-layout simulation using Cadence 45nm
- Reduced CPI by 19% through the implementation of basic bypass and stall units
- Emulated I/D cache using registers and improved instruction memory locality by 30% by eliminating unnecessary NOPs

ReRAM Based Computing-in-Memory Macro for CNN-Based Edge Processors

National Tsing Hua University (Memory Lab)

Sep. 2022 – May 2023

- Developed multiply-accumulate units with CIM structure instead of conventional Von-Neumann architecture under TSMC 0.18um technology
- Reduced 1/4 power consumption by Down-Scaling Weighted Current Translator
- Increased 2x outputs possibility by integrating Triple Margin Current Sensed Amplifier and Accumulator
- Won the first prize of the TSMC research assistant fellowship with 50,000 NTD

Multiclass Image Classification on BIRDS 525 SPECIES dataset by CNN

National Tsing Hua University

Nov. 2023 – Jan. 2024

- Implemented with PyTorch and scikit-learn libraries
- Built a deep learning pipeline with pretrained ResNet-18 model to classify 525 bird species from high-variance image data, and add custom layers to improve generalization
- Applied random crop, flip and normalization on images to address class imbalance and overfitting

Full-Custom IC Design for ReRAM ROM (128x16bits) macro

National Tsing Hua University

Sep. 2022 – Jan. 2023

- Directed the weekly meeting, assigned tasks, and proposed the ROM macro structure
- Integrated decoders, mux, sensing amplifiers, and clock generator
- Initiated from schematic entry, pre-simulation, layout, DRC/LVS, RC extraction, and post-simulation under TSMC 0.18um technology

Low Dropout Regulator (LDO) combined with Bandgap Reference

National Tsing Hua University

Sep. 2022 – Jan. 2023

- Simulated a PMOS-based Low Dropout Regulator (LDO) with a precision Bandgap Reference using HSPICE and WaveView, delivering a stable 1.6V output from a $1.8V \pm 10\%$ supply
- Met all design specifications including $<100 \mu V^{\circ}C$ temperature coefficient, DC PSR <-60 dB, 100 kHz PSR <-40 dB, and LDO phase margin $>65^{\circ}$ under a 100 mA, 50 pF load
- Engineered a custom high-gain error amplifier to meet stringent PSR requirements, ensuring robust output regulation and noise rejection

CERTIFICATE & FELLOWSHIP

Professional Course Learning Honor Certificate x 2

National Tsing Hua University

Sep. 2022, Sep. 2023

Top 10% of the college

NVIDIA Deep Learning Institute Certificate

NVIDIA

Building Transformer-Based Natural Language Processing Applications

Dec. 2023

First Prize of the TSMC Research Assistant Fellowship

TSMC

Awarded with 50,000 NTD fellowship

May 2023

Quality Champion Award 2025 – On-time Delivery

SiFive

Recognized for on-time delivery and workflow excellence

Nov. 2025

TECHNICAL SKILLS

Programming: C/C++, Python, git, RISC-V assembly, scala

IC Design Tools: Verilog, System Verilog, Chisel HDL, Hammer, Synopsys Custom WaveView, Verdi, Laker, Design Compiler, Cadence Innovus, Virtuoso, conformal LEC, HSPICE